

Bid Bulletin No. 3

**Consulting Service for the Updating of the Semiconductor and Electronics Industry Roadmap, and the Conduct of Feasibility Study on Establishing a Wafer Fabrication Plant
Bidding No. 24-010**

June 6, 2024

This Bid Bulletin No. 3 is hereby issued to modify or amend the Bidding Documents.

Schedule of Proceedings

Activity	Schedule
Pre-Bid Conference	18 June 2024, 9:30 AM, for the Pre-Bid Conference through video conference with the following details: Zoom Meeting: https://zoom.us/j/97584075325?pwd=TzdCWIFDVms3Z25wSzZrb3FEK2N3UT09 Meeting ID: 975 8407 5325 Passcode: BAC2024
Submission of Technical and Financial Documents and Opening of Technical Documents	01 July 2024, 9:00 AM, for the Submission of Technical and Financial Documents, and 9:30 AM for the Opening of Technical Documents through video conference with the following details: Zoom Meeting: https://zoom.us/j/92591496357?pwd=TGHlZFJWwVI3dHdxRmlaUIVU2MwZz09 Meeting ID: 925 9149 6357 Passcode: BAC2024
Opening of Financial Documents	08 July 2024, 9:30 AM, for the Opening of Financial Documents through zoom video conference with the following details: Zoom Meeting: https://zoom.us/j/96342631535?pwd=n8iL8ZRaiRYHaHkUKyrtTIDgoxK1qZ.1 Meeting ID: 963 4263 1535 Passcode: BAC2024

For the guidance and information of all concerned.

SGD.
KRISTIAN R. ABLAN
Assistant Secretary
Chairperson, DTI Bids and Awards Committee

Conforme:

Name and Signature of
Authorized Representative
Date: _____